

## Electronic Patent Application Fee Transmittal

Application Number:	10750059			
Filing Date:	30-Dec-2003			
Title of Invention:	Solder ball pad structure			
First Named Inventor:	Hiroshi Miyazaki			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-36833			

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	120	120
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>120</b>